

Product Datasheet

Copper Wafer

Product code: CU-M-04-WF

Formula: Cu

Molecular Weight: 63.55

Purity: (4N) 99.99%

CAS No.: 7440-50-8

EC No.: 231-159-6

MDL: MFCD00010965

Appearance: Reddish Metal

Melting Point: 1085 °C

Boiling Point: 2562 °C

Density: 8.96 g/cm³

Total Metal Impurities (max): 0.01%

Documentation

A Certificate of Analysis and Materials Safety Data Sheet (SDS) in accordance with EN 10204 are supplied with every shipment.

Note

The above information is believed to be correct but does not purport to be all inclusive and shall be used only as a guide. The information in this document is based on the present state of our knowledge and is applicable to the product with regard to appropriate safety precautions. It does not represent any guarantee of the properties of the product. American Elements shall not be held liable for any damage resulting from handling or from contact with the above product.